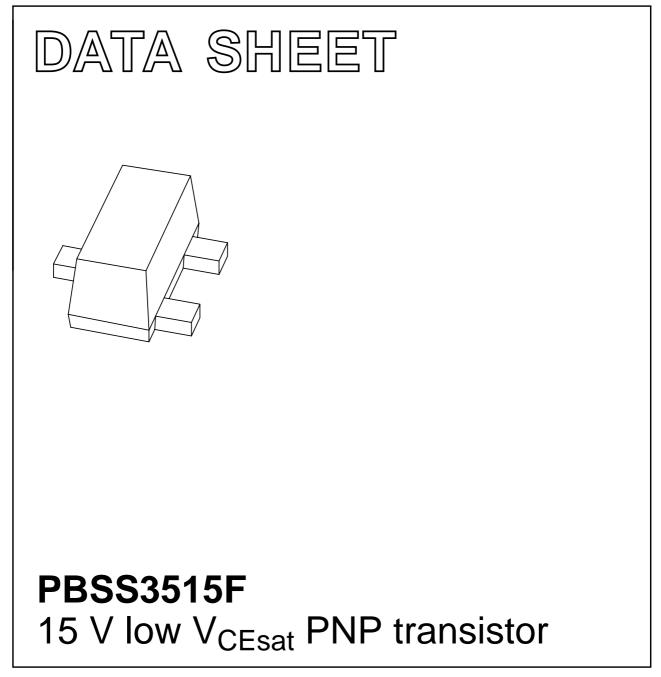
# DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2001 Jan 26 2001 Sep 21



### FEATURES

- Low collector-emitter saturation voltage
- High current capabilities
- Improved thermal behaviour due to flat leads.

### APPLICATIONS

- General purpose switching and muting
- Low frequency driver circuits
- LCD backlighting
- Audio frequency general purpose amplifier applications
- Battery driven equipment (mobile phones, video cameras and hand-held devices).

#### DESCRIPTION

PNP low  $V_{CEsat}$  transistor in a SC-89 (SOT490) plastic package. NPN complement: PBSS2515F.

#### MARKING

TYPE NUMBER	MARKING CODE		
PBSS3515F	2B		

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	МАХ	UNIT
V <sub>CEO</sub>	emitter-collector voltage	–15	V
I <sub>C</sub>	collector current (DC)	-500	mA
I <sub>CM</sub>	peak collector current -1		А
R <sub>CEsat</sub>	equivalent on-resistance <500		mΩ

#### PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	

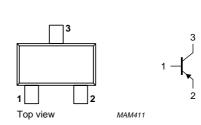


Fig.1 Simplified outline (SC-89; SOT490) and symbol.

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	–15	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	–15	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	-6	V
I <sub>C</sub>	collector current (DC)		-	-500	mA
I <sub>CM</sub>	peak collector current		-	-1	А
I <sub>BM</sub>	peak base current		-	-100	mA
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$	-	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

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### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R <sub>th j-a</sub>	thermal resistance from junction to ambient	in free air	500	K/W	

### CHARACTERISTICS

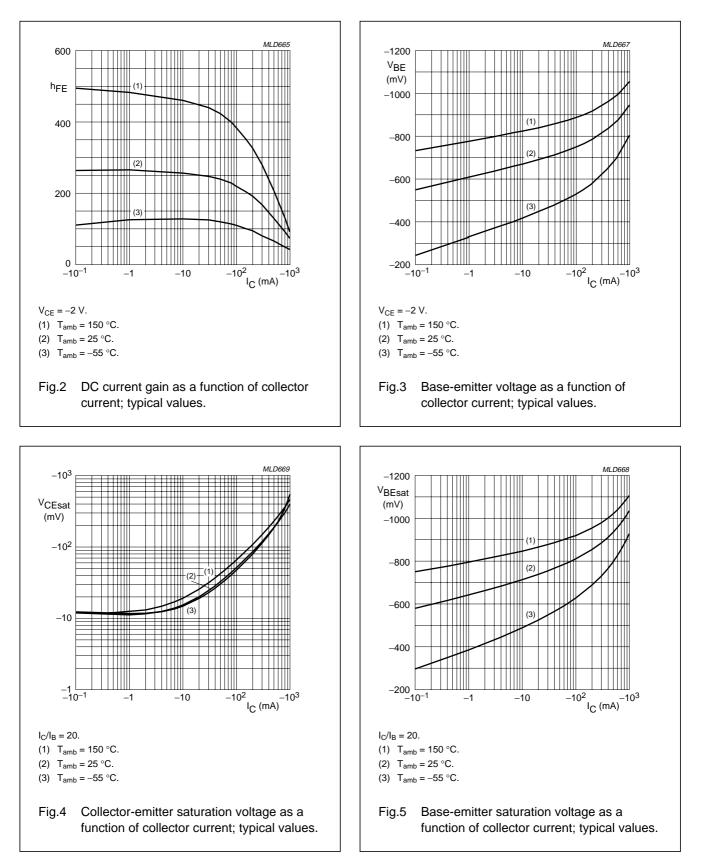
 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -15 \text{ V}; I_E = 0$	-	-	-100	nA
		$V_{CB} = -15 \text{ V}; I_E = 0; T_j = 150 \text{ °C}$	-	-	-50	μA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 V; I_{C} = 0$	-	-	-100	nA
h <sub>FE</sub>	DC current gain	$V_{CE} = -2 \text{ V}; \text{ I}_{C} = -10 \text{ mA}$	200	-	-	
		$V_{CE} = -2 \text{ V}; \text{ I}_{C} = -100 \text{ mA}; \text{ note } 1$	150	-	-	
		$V_{CE} = -2 \text{ V}; \text{ I}_{C} = -500 \text{ mA}; \text{ note } 1$	90	-	-	
V <sub>CEsat</sub>	collector-emitter saturation	$I_{\rm C} = -10 \text{ mA}; I_{\rm B} = -0.5 \text{ mA}$	-	-	-25	mV
	voltage	$I_{\rm C} = -200 \text{ mA}; I_{\rm B} = -10 \text{ mA}$	-	-	-150	mV
		$I_{C} = -500 \text{ mA}; I_{B} = -50 \text{ mA}; \text{ note } 1$	-	-	-250	mV
R <sub>CEsat</sub>	equivalent on-resistance	$I_{C} = -500 \text{ mA}; I_{B} = -50 \text{ mA}; \text{ note } 1$	-	300	<500	mΩ
V <sub>BEsat</sub>	base-emitter saturation voltage	$I_{C} = -500 \text{ mA}; I_{B} = -50 \text{ mA}; \text{ note } 1$	-	-	-1.1	V
$V_{BE}$	base-emitter turn-on voltage	$V_{CE} = -2 \text{ V}; \text{ I}_{C} = -100 \text{ mA}; \text{ note } 1$	-	-	-0.9	V
f <sub>T</sub>	transition frequency	$I_{C} = -100 \text{ mA}; V_{CE} = -5 \text{ V};$ f = 100 MHz	100	280	-	MHz
C <sub>c</sub>	collector capacitance	$V_{CB} = -10 \text{ V}; I_E = I_e = 0; f = 1 \text{ MHz}$	-	-	10	pF

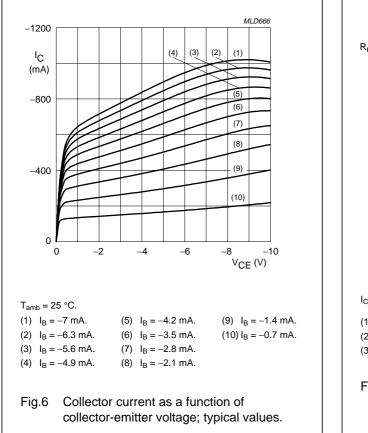
#### Note

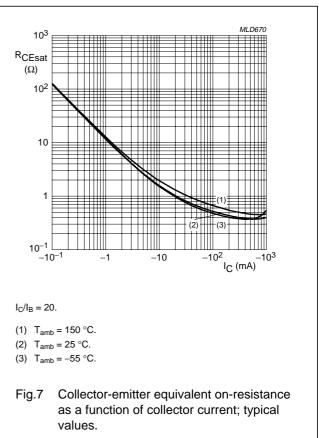
1. Pulse test:  $t_p \leq 300 \ \mu s; \ \delta \leq 0.02.$ 

# PBSS3515F



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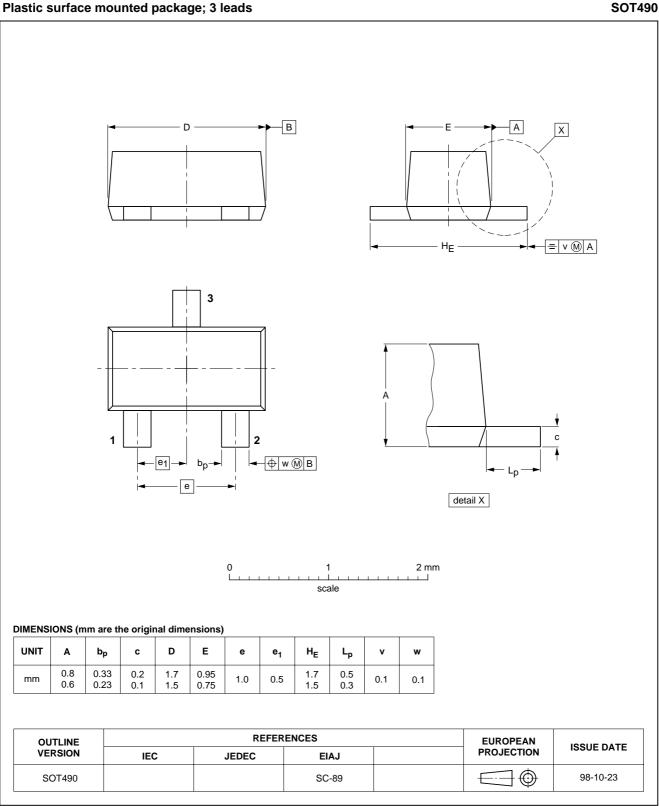




PBSS3515F

# 15 V low V<sub>CEsat</sub> PNP transistor

### PACKAGE OUTLINE



# 15 V low $V_{CEsat}$ PNP transistor

PBSS3515F

#### DATA SHEET STATUS

DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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For additional information please visit http://www.semiconductors.philips.com. Fax: +31 40 27 24825 For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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